

## **ECE6229 Introduction to MEMS    Fall 2011**

### **Text Books:**

“Fundamentals of Microfabrication and Nanotechnology,” Third Edition by M. Madou, CRC Press, 2010.

### **References:**

“An Introduction to Microelectromechanical Systems Engineering,” 2<sup>nd</sup> Edition by N. Maluf and K. Williams, Artech House Inc., 2004.

“Silicon Processing for the VLSI Era – Volume 1 Process Technology,” by S. Wolf and R.N. Tauber, Lattice Press, 2002.

“The Science and Engineering of Microelectronic Fabrication,” by S. A. Campbell, Oxford, 2001 (2<sup>nd</sup> Edition)

Lecture Time:    MW 3:05am – 3:55am

Place: TBD

Lab: Wed, Th or Fri 9:05am – 11:55am

Marcus Technology Building Clean Room

MiRC Clean Room SEM Microscopy and AFM Laboratory

Instructors:

**Bruno Frazier or Todd Sulchek,**

Room 203 MiRC    Room 310, Love Building,

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**Grading:**    Homework: 10%  
                  Exam I: 25%, Exam II: 25%,  
                  Lab: 30%  
                  Term Paper: 10%

**Honor Code:** <http://www.honor.gatech.edu>

		<b>FALL 2011</b>		
		<b>ECE 6229 Introduction to MEMS</b>	<b>Madou</b>	<b>Homework</b>
<b>Date</b>	<b>Lecture</b>	<b>Topic</b>	<b>Book</b>	<b>Project</b>
8/17/2011	1	Introduction and scaling laws	9	
8/19/2011	2	Introduction to lithography	1	
8/24/2011	3	Mask aligner and imaging optics	1	
8/26/2011	4	Resolution in photolithography and mask layout	1	A1
8/31/2011	5	Structure of silicon and properties		
9/2/2011	6	Oxidation and diffusion	4	D1,A2
9/7/2011		<b>Labor day</b>	3	
9/9/2011	7	Nucelation and growth	3, 5	D2,A3
9/14/2011	8	Evaporation	3	
9/16/2011	9	Sputtering	3	D3, A4
9/21/2011	10	CVD	3	
9/23/2011	11	PECVD	3	D4, A5
9/28/2011	12	Atomic Layer Deposition	-	
9/30/2011	13	Polysilicon	5	D5
10/7/2011	14	Wet etching	2	
10/12/2011	15	Surface micromachining	5	
10/14/2011		Bulk micromachining processes		
10/19/2011	16	Corner compensation and etch stop	4	PA
10/21/2011	17	<b>Midterm</b>	4	A6
10/26/2011	18	Vacuum physics and kinetic thoery		
10/28/2011	19	Plasma etching	2	D6,A7
11/2/2011	20	Deep RIE etching	2	
11/4/2011	21	Characterization Methods	8	D7,A8
11/9/2011	22	Wafer anodic bonding and local bonding	6	
11/11/2011	23	Stereolithography	6	D8,A9
11/16/2011	24	PDMS and SU-8 MEMS processing	-	
11/18/2011	25	Electroplating metals	-	
11/23/2011	26	MEMS/NEMS Sensors	6	D9,A10
11/25/2011	27	Microcantilever Fabrication Processes	10	
11/30/2011	28	Student presentations	10	D10
12/2/2011	29	Student presentations	-	
12/7/2011		<b>Final Exam</b>		PD
		Project - critical review of MEMS processing		
	Lab	<b>LABORATORY EXPERIMENTS FOR MEMS CLASS</b>		
	1	Lab safety and clean room protocol and wafer cleaning		
	2	Parylene deposition/PDMS molding		
	3	CAD and Mask Making		
	4	Electroplating		
	5	Photolithography		
	5	Silica Etching and Bulk Silicon Micromachining		
	6	Characterization Methods		
	7	Aluminum deposition		
	8	Anodic bonding		

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